

WHAT IS CLAIMED IS:

1. An aggregate of electronic components comprising:
one substrate; and
three or more electronic components including an
5 element and an electronic component, formed on the one
substrate, forming an aggregated planar surface on a
surface of the substrate.
2. An aggregate of electronic components comprising:
one substrate; and
10 two or more types of electronic components
including an element and an electronic component, formed on
the one substrate, and forming an aggregated planar surface
on a surface of the substrate.
3. An aggregate of electronic components according
15 to Claim 1, wherein each of said electronic components is
formed on an upper surface of the substrate, and electrodes
corresponding thereto are formed on the upper surface and a
side surface of the substrate so as to be connected with
other element or component on an upper surface side of the
20 substrate.
4. An aggregate of electronic components according
to Claim 2, wherein each of said electronic components is
formed on an upper surface of the substrate, and electrodes
corresponding thereto are formed on the upper surface and a
25 side surface of the substrate so as to be connected with

00802745-062801

other element or component on an upper surface side of the substrate.

5. A method for mounting an aggregate of electronic components comprising:

5 reversing a substrate, comprising three or more, or two or more types of electronic components including an element and an electronic component on an upper surface thereof, and electrodes corresponding thereto at least on the upper surface out of the upper surface and a side
10 surface thereof so as to be connected to other element or component on said upper surface, in such a manner that the upper surface is directed downward; and

thereafter mounting the substrate on a mounting object to connect the electrodes of the substrate to a side
15 of the mounting object.

6. An aggregate of electronic components comprising:
a substrate; and

three or more, or two or more types of electronic components including an element and an electronic component
20 and formed on the substrate, with electrodes corresponding thereto being formed at least on a lower surface of the lower surface and a side surface of the substrate so as to be connected to other element or component on the lower surface thereof, and with the electrodes provided on the
25 lower surface of the substrate being connected to

09092746.052804

electronic components formed on an upper surface of the substrate via the side surface of the substrate and/or a through hole.

7. An aggregate of electronic components comprising:

5 one substrate; and

a plurality of electronic components including an element and an electronic component and distributed to an upper surface and the lower surface of the one substrate, with electrodes of the electronic component formed on the upper surface being formed on a side surface of the substrate and with the electrodes of the electronic component formed on the lower surface are formed on the lower surface of the substrate.

8. An aggregate of electronic components comprising:

15 one substrate; and

electronic components including an element and an electronic component and distributed to an upper surface and a lower surface of the one substrate, with the electrodes of the electronic component formed on the upper surface being formed on a side of the substrate and with electrodes of the electronic component formed on the lower surface being formed on a side surface of the substrate having no electrode of the electronic component formed on the upper surface.

25 9. An aggregate of electronic components according

00892745-062801

to Claim 7, wherein the electronic components formed on the upper and lower surfaces of the substrate are resistors.

10. An aggregate of electronic components according to Claim 8, wherein the electronic components formed on the upper and lower surfaces of the substrate are resistors.

11. An aggregate of electronic components comprising:
a substrate, inside of which a capacitor or an inductor is formed; and

an electronic component formed on an upper surface and/or a lower surface of the substrate.

12. An aggregate of electronic components comprising:
one substrate; and

two or more resistors formed on the one substrate, and set in advance to resistance values different from each other by trimming so as to have resistance values required on a target connecting circuit.

13. A mobile device comprising:

a circuit substrate having a wiring pattern; and
the aggregate of electronic components according

to Claim 1 which is mounted on the circuit substrate so that electrodes of the substrate and the wiring pattern of the circuit substrate are connected.

14. A mobile device comprising:

a circuit substrate having a wiring pattern; and
the aggregate of electronic components according

09892746-052804
F08290-942880

to Claim 2 which is mounted on the circuit substrate so that electrodes of the substrate and the wiring pattern of the circuit substrate are connected.

15. A mobile device comprising:

5 a circuit substrate having a wiring pattern; and
the aggregate of electronic components according to Claim 6 which is mounted on the circuit substrate so that electrodes of the substrate and the wiring pattern of the circuit substrate are connected.

10 16. A mobile device comprising:

a circuit substrate having a wiring pattern; and
the aggregate of electronic components according to Claim 7 which is mounted on the circuit substrate so that electrodes of the substrate and the wiring pattern of
15 the circuit substrate are connected.

17. A mobile device comprising:

a circuit substrate having a wiring pattern; and
the aggregate of electronic components according to Claim 8 which is mounted on the circuit substrate so
20 that electrodes of the substrate and the wiring pattern of the circuit substrate are connected.

18. A mobile device comprising:

a circuit substrate having a wiring pattern; and
the aggregate of electronic components according to Claim 12 which is mounted on the circuit substrate so
25

00002746.062804

that electrodes of the substrate and the wiring pattern of the circuit substrate are connected.

5

09092745.062804